

# **HVD359**

# Variable Capacitance Diode for VCO

REJ03G0500-0300 Rev.3.00 Jan 24, 2006

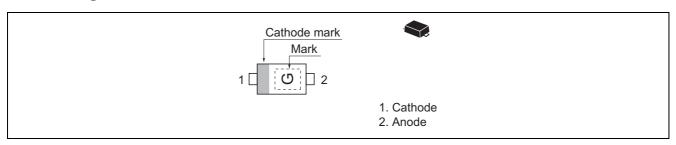
#### **Features**

- High capacitance ratio and good C-V linearity.
- To be usable at low voltage.
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

### **Ordering Information**

| Type No. | Laser Mark | Package Name | Package Code |  |
|----------|------------|--------------|--------------|--|
| HVD359   | G          | SFP          | PUSF0002ZB-A |  |

# **Pin Arrangement**



# **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

| Item                 | Symbol         | Value       | Unit |
|----------------------|----------------|-------------|------|
| Reverse voltage      | V <sub>R</sub> | 15          | V    |
| Junction temperature | Tj             | 125         | °C   |
| Storage temperature  | Tstg           | -55 to +125 | °C   |

### **Electrical Characteristics**

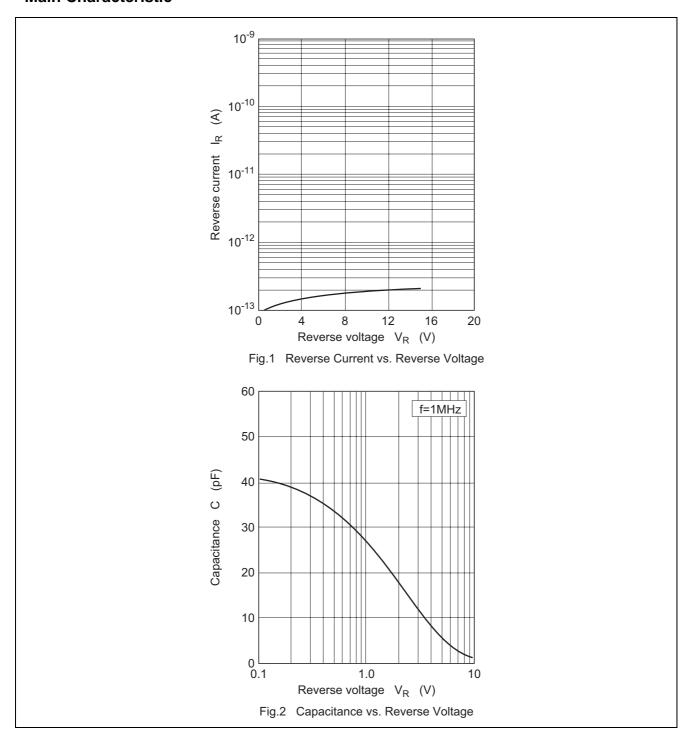
 $(Ta = 25^{\circ}C)$ 

| Item              | Symbol          | Min  | Тур | Max  | Unit | Test Condition                                    |
|-------------------|-----------------|------|-----|------|------|---|
| Reverse current   | I <sub>R1</sub> | _    | _   | 10   | nA   | V <sub>R</sub> = 10 V                             |
|                   | I <sub>R2</sub> | _    | _   | 100  |      | V <sub>R</sub> = 10 V, Ta = 60°C                  |
| Capacitance       | C <sub>1</sub>  | 24.8 | _   | 29.8 | pF   | V <sub>R</sub> = 1 V, f = 1 MHz                   |
|                   | C <sub>4</sub>  | 6.00 | _   | 8.30 |      | V <sub>R</sub> = 4 V, f = 1 MHz                   |
| Capacitance ratio | n               | 3.00 | _   | _    | _    | C <sub>1</sub> /C <sub>4</sub>                    |
| Series resistance | r <sub>S</sub>  | _    | _   | 1.50 | Ω    | V <sub>R</sub> = 4 V, f =100 MHz                  |
| ESD-Capability *1 |                 | 200  | _   | _    | V    | $C = 200 \text{ pF}, R = 0 \Omega$ , Both forward |
|                   |                 |      |     |      |      | and reverse direction 1 pulse.                    |

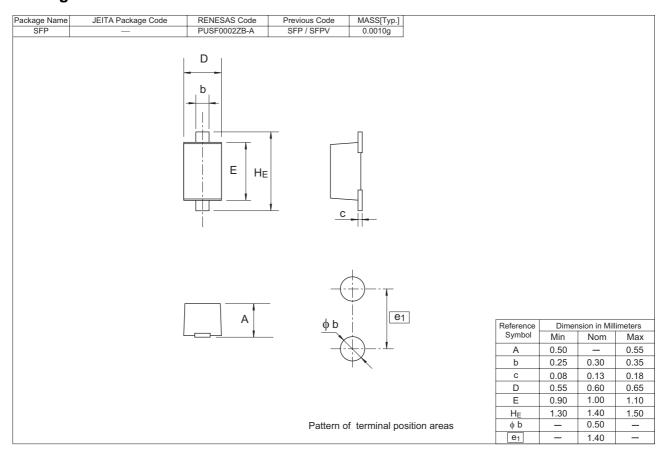
Notes: 1. Failure criterion ;  $I_R \ge 20$  nA at  $V_R = 10$  V

2. For SFP package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

# **Main Characteristic**



# **Package Dimensions**



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